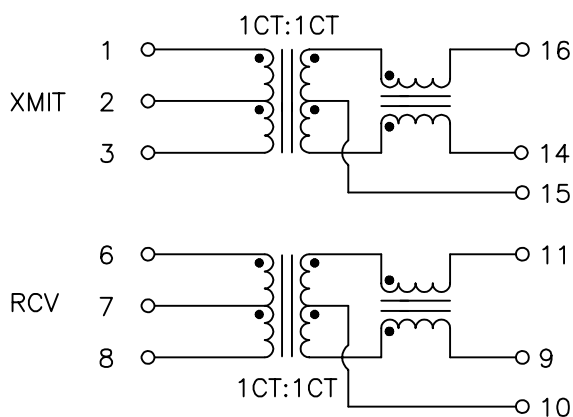


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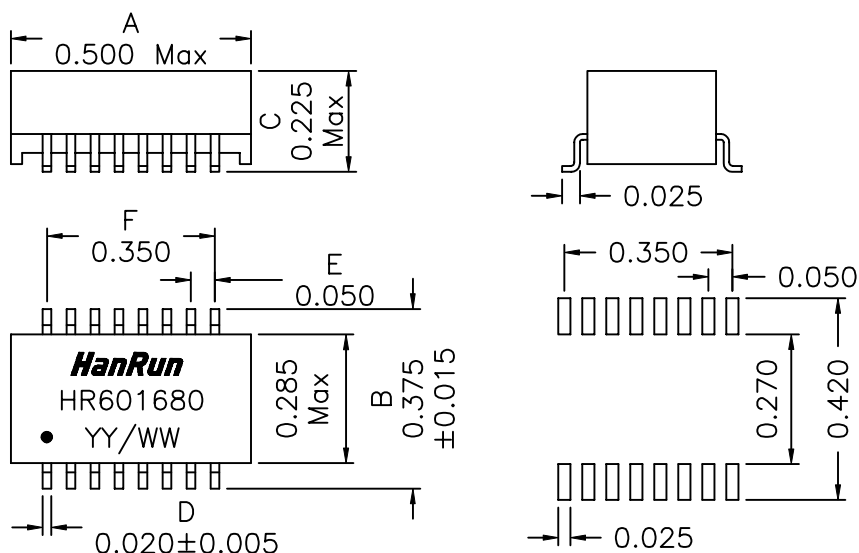
Electrical Specification @25°C

- Operating Temperature Range: 0°C ~ +70°C
- Isolation: 1500Vrms 0.5mA 60sec (Primary to Secondary)
- OCL: 350uH Minimum @100KHz 100mV with 8mADC
- Insertion Loss: -1.1dB Maximum @300KHz ~ 100MHz
- Return Loss: -20dB Typical @30MHz
 - 14dB Typical @60MHz
 - 11.5dB Minimum @80MHz
- Different to Common Mode Rejection: -37dB Typical @30MHz ~ 50MHz
 - 30dB Typical @100MHz
- Crosstalk: -45dB Typical @1MHz ~ 30MHz / -35dB Typical @60MHz ~ 100MHz

Schematics



Mechanical Dimensions



Case material: DAP

Dimensions in inches

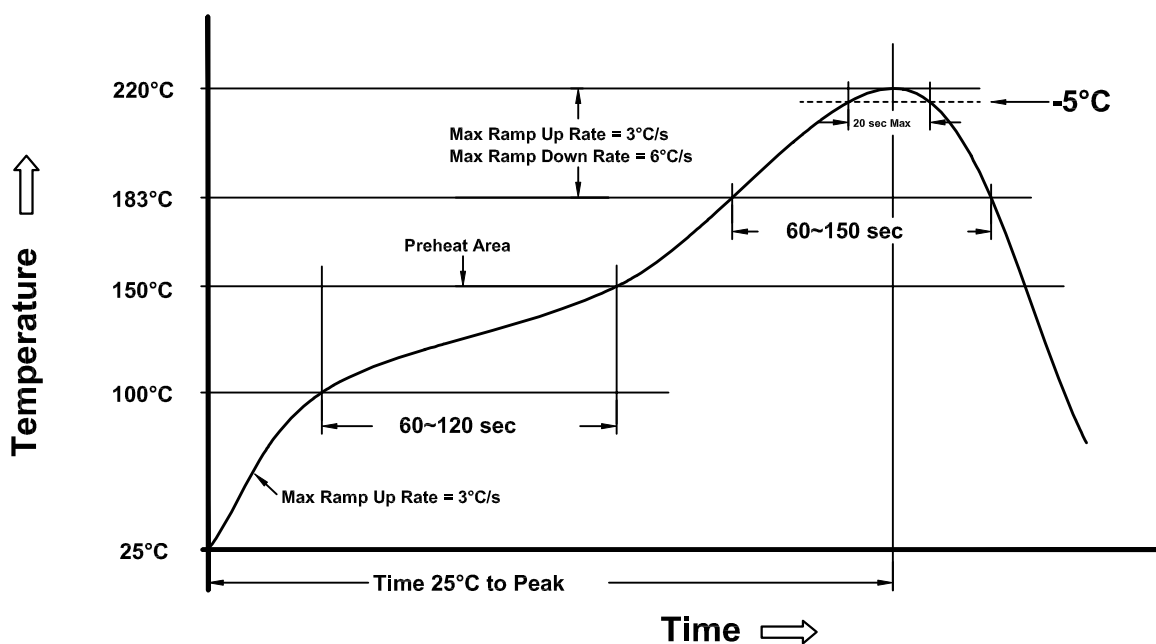
Unless otherwise specified, Tolerance: .xxx ±0.010

REV.: B

SUGGESTED PCB PAD LAYOUT

HR601680

Recommended Soldering Profile



Remarks:

- peak temperature (T_p)= 220°C
- Maximum preheat rate = 3°C / sec
- Ramp up rate = 3°C / sec max
- Time above 183°C = 60 sec min / 150 sec max
- Maximum cooling rate = 6°C / sec
- T 25°C to peak = 6 min max
- preheat Time = 60 ~ 120 sec
- The number of allowed cycles in IR reflow ≤ 2 cycles